



Product Change Notification

Change Notification #: 117077 - 00
Change Title: Intel® Server System R2312WF0NP, PCN 117077-00, Label, System outer box stacking logo update
Date of Publication: July 25, 2019

Key Characteristics of the Change:

Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	August 9, 2019
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following changes on the Intel® Server System R2312WF0NP:

Intel is updating the system outer box stacking logo, original logo mean MAX 7-layers in total, however, only 6-layers as MAX can be supported by logistics racking limitation.

	Original outer box	New outer box
IPN	J33994-001	J33994-002
Description	System outer box with J33994-001 IPN and 6 layers stacking logo printing	Updated system outer box with J33994-002 IPN and 5 layers stacking logo printing
Photos		

Image 1. Power supply label before change

Image 2. Power supply label after change

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from this change, but encourages customers to understand the change and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
R2312WF0NP	975812	J43224-010	J43224-011

PCN Revision History:

Date of Revision:

July 25, 2019

Revision Number:

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Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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